

Reflector cavity packaging for UV LEDs

Dr. Ulli Hansen - CEO



Lithoglas – Company Overview



Brief Company History

- Germany based company, Founded in 2006
- Headquarters and Production in Dresden
- ➤ R&D Cooperation in Berlin
- ISO 9001 certified since 2011



Purpose:

Develop and commerzialize innovative wafer level packaging technologies for enabling miniaturized SMD or COB-type packages

Application Focus:

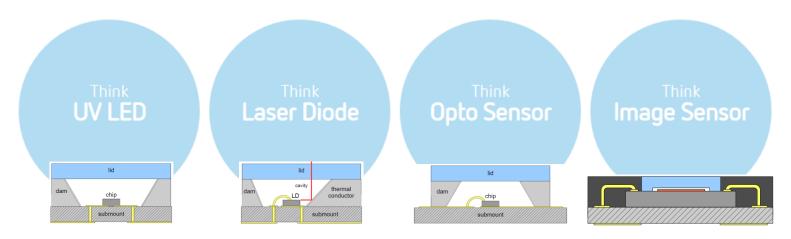
Opto-Electronic Packaging and MEMS

Lithoglas - Company Overview



Lithoglas – Specialist in advanced opto-electronic packaging

- Enabling Miniaturized, Hermetic, SMD-/COB-compatible Packages
- Enhancing Optical Performance
- Excellent precision due to semiconductor processing techniques
- High scalability by wafer-level processing
- Focus on Emitter and Sensor Packaging for:

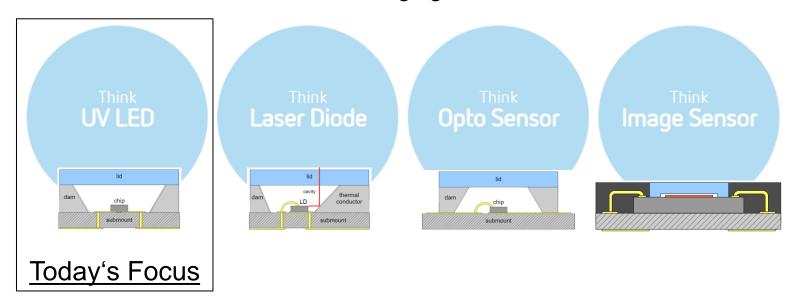


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Examples from the internet

DUV LED – Current Packaging



TO – package

- hermetic, welded package
- ➤ large, cumbersome mounting
- ➤ integration of lenses possible
- suitable for lower volumes



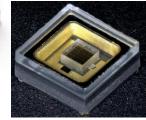


SMD ceramic packages

➤ 3D-structured ceramic / through contacts to back

hermeticity possible, quartz lid e.g. attached by AuSn soldering

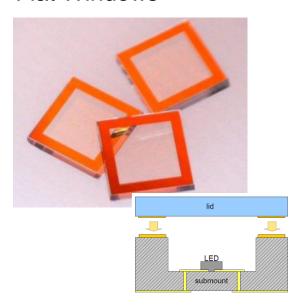






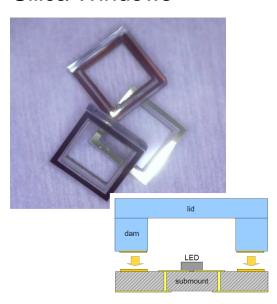
Our offerings for SMD-type packaging of UV-LEDs

Flat Windows

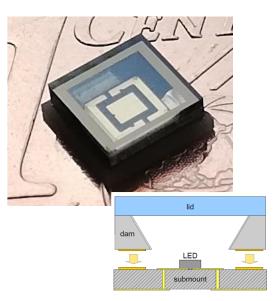


- Drop in solution for current packages
- Silica lid
- High performance AR coatings
- Solderable metallization

Silica Windows



- Allows use of flat submount
- Transparent sidewalls
- > 3D-structured silica cap
- High performance AR coatings
- Solderable metallization

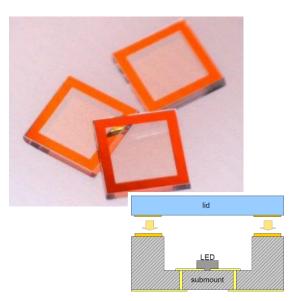


- Allows use of flat submount
- Integrates reflector mirrors
- Silica lid
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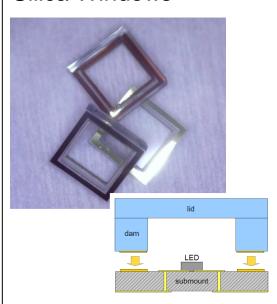
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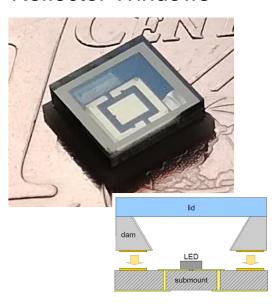


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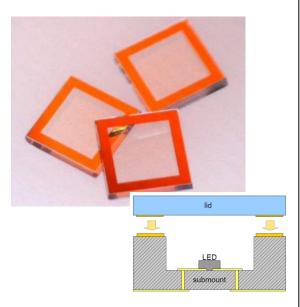


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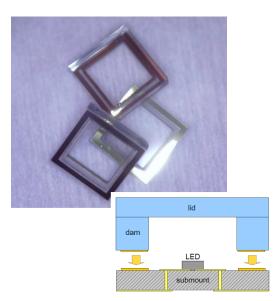
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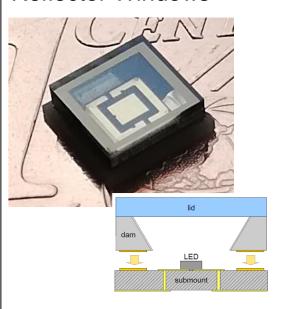


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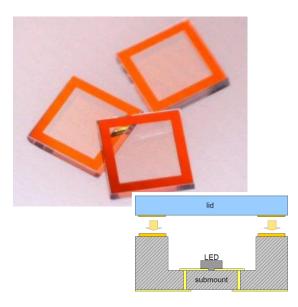


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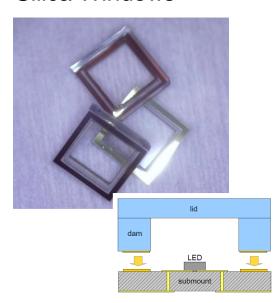
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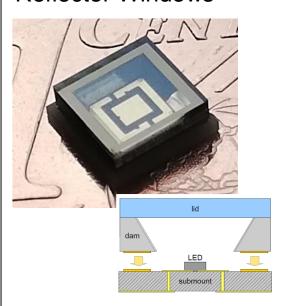


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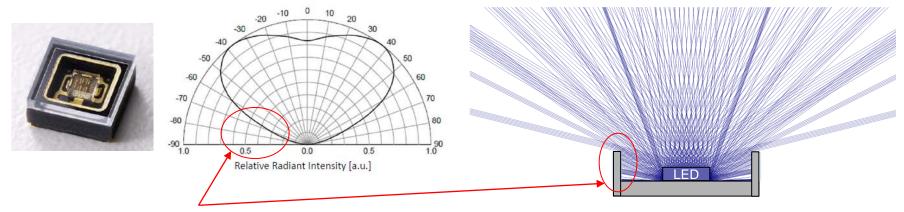
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DUV LED – Light Output



Radiation pattern:

➤ LEDs emit a significant amount of light towards the side

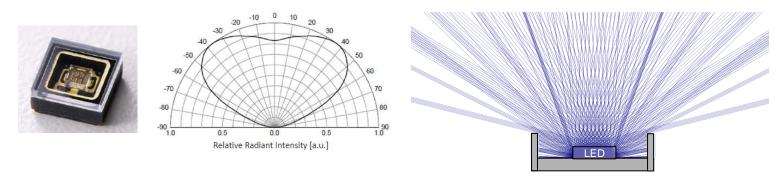


➤ Large amount of generated light is lost at the side walls of the package

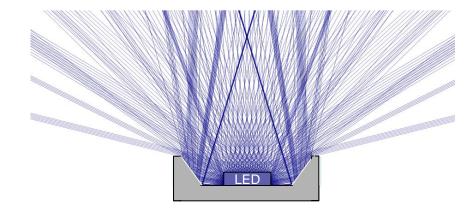
DUV LED – Light Output



Radiation pattern:



- reflector allows to redirect side-emitted light to the top
- Higher output power!
- Comparison measurements to bare LED on submount (no lid) show that about 97% of the light is emitted by the reflector package



- Better thermal performance!
- Less light is lost in the sidewalls, less light is reflected back onto the LED.
- Less heat generated in the package: LED current can be increased for higher light output

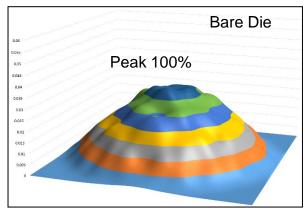
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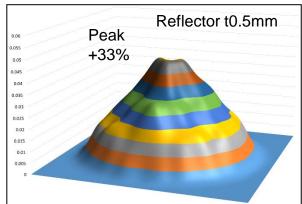


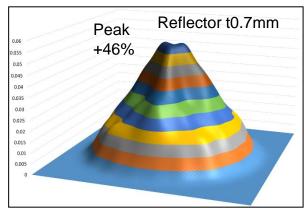
Design Options:

reflector height allows to center the light pattern

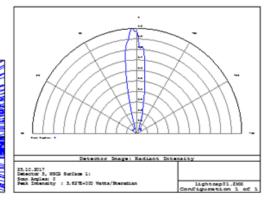
Radiant Intensity (simulated):







- simulations show: lens-type emission pattern can be achieved maintaining a flat window surface!
- evaluation work on-going

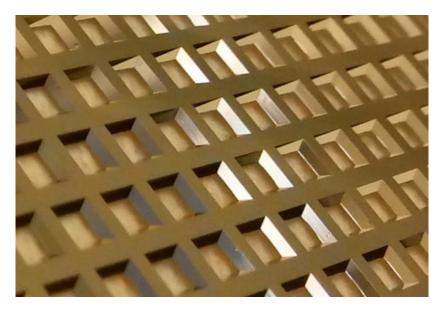


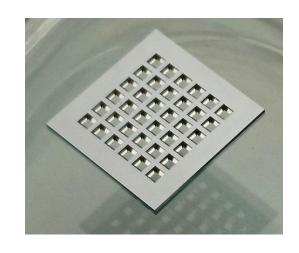
DUV LED - Reflector Arrays

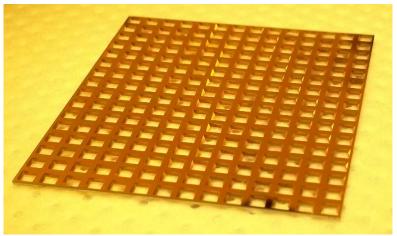


Lithoglas array package

- > cap array can be integrated in single package
- each LED with individual reflector
- optical insulation of single LEDs
- improved optical and thermal performance
- > customized sizes feasible







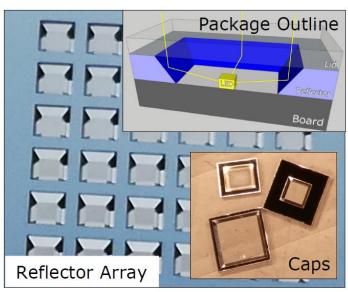
Summary



Conventional Packages



Lithoglas Package



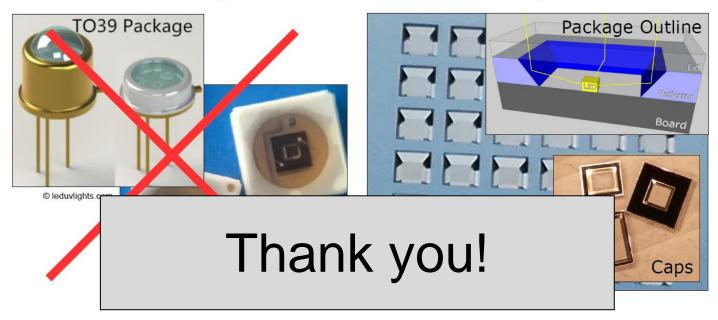
- high light output by integrated reflector
- good thermal performance
- hermeticity possible, fully inorganic materials
- customized package outlines and arrays possible
- integration in standard 3535 packages possible

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